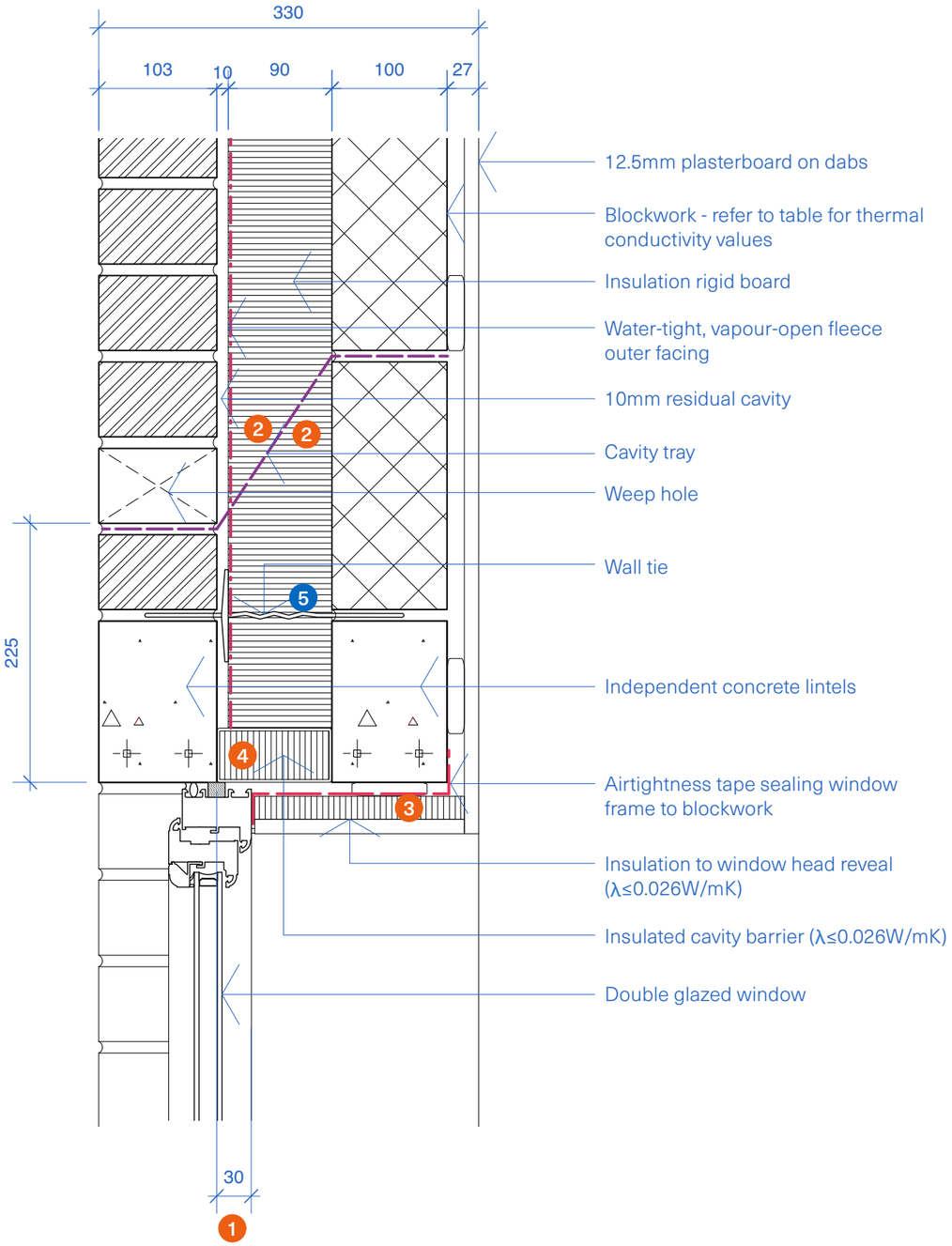
Construction Detail



Calculated Ψ (Psi) value for use in SAP Calculation

	Internal leaf block thermal conductivity (W/mK)					
Insulation thermal conductivity (W/mK)	0.11	0.15	0.19	0.28	0.6	1.33
0.019	**0.022**	**0.020**	**0.019**	**0.017**	**0.016**	**0.015**
0.022	**0.022**	**0.020**	**0.018**	**0.017**	**0.014**	**0.014**

f-values: 0.957 - 0.961 (values above 0.75 indicate low risk of condensation and mould)

Ψ (Psi) value Thermal Compliance Notes

1. Minimum 30mm overlap of window frame and insulated wall cavity.
2. Ensure insulation rigid board is cut and fitted around the angle of the cavity tray.
3. Minimum 15mm insulation with λ≤0.026W/mK to head reveal.
4. Insulated cavity barrier with λ≤0.026W/mK fixed in accordance with maufacturers guidelines. If fixing spikes are used, they should be installed at the required centres. For compression fit cavity barriers, use the correct size for a compressive fit in the cavity.

Construction Notes

5. Wall tie: 225mm maximum distance from opening. No greater than 450mm vertical spacing.
450mm horizontal centres for first row of wall ties above and below opening.
Only use insulation retaining clips that are compatible with the wall tie.

General Notes

The cavity must be closed at the top of the wall and openings for the provisions of Diagram 5.3 ADBv1 to apply.